intersil

HS-82C08RH

Radiation Hardened 8-Bit Bus Transceiver

February 1996

Features

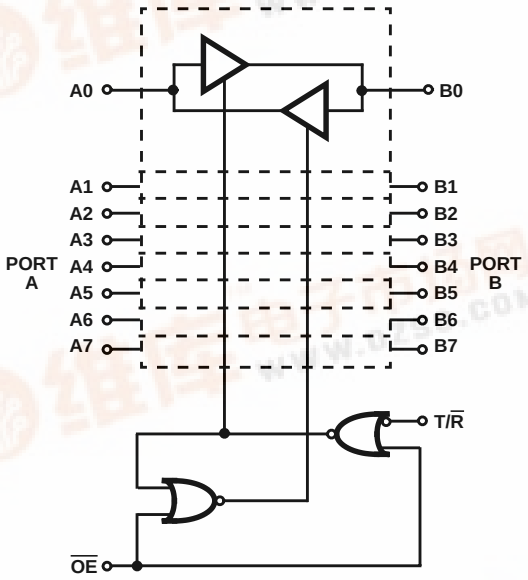
- Devices QML Qualified in Accordance With MIL-PRF-38535
- Detailed Electrical and Screening Requirements are Contained in SMD# 5962-95714 and Intersil' QM Plan
- Radiation Hardened
  - Total Dose 1 x 10^5 RAD (Si)
  - Latch-Up Immune EPI-CMOS > 1 x 10^{12} RAD (Si)/s
- Bidirectional Three-State Input/Outputs
- Low Propagation Delay Time
- Low Power Consumption
- Single Power Supply +5V
- Electrically Equivalent to Sandia SA2997
- Military Temperature Range -55°C to +125°C

Description

The Intersil HS-82C08RH is a radiation-hardened octal bus transceiver with three-state outputs. It is manufactured using a self-aligned, junction isolated CMOS process and is designed for use with the HS-80C08RH radiation-hardened microprocessor. The HS-82C08RH allows asynchronous two-way communication between data buses. The direction of data flow is determined by the logic level on the transmit/receive (T/$\overline{R}$) input. A logic high on the T/$\overline{R}$ input specifies data flow from Port A to Port B of the device. Conversely, a logic low on the T/$\overline{R}$ input specifies data flow from Port B to Port A. The Output Enable input disables both ports by placing them in the high impedance state.

The HS-82C08RH is ideally suited for a wide variety of buffering applications in radiation-hardened microcomputer systems.

Functional Diagram



TRUTH TABLE

INPUTS		OPERATION	
OUTPUT ENABLE	TRANSMIT /RECEIVE	PORT A	PORT B
0	0	Out	In
0	1	In	Out
1	X	High Z	High Z

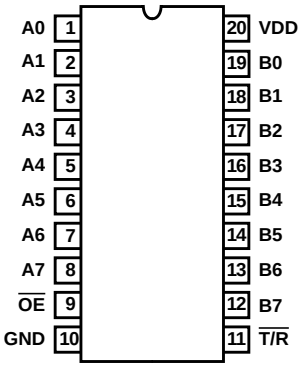
X = Don't Care

Ordering Information

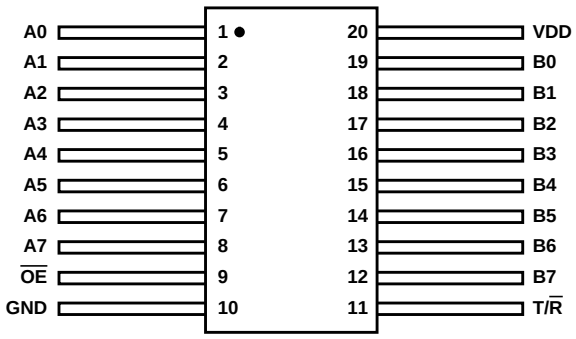
PART NUMBER	TEMPERATURE RANGE	SCREENING LEVEL	PACKAGE
5962R9571401QRC	-55°C to +125°C	MIL-PRF-38535 Level Q	20 Lead SBDIP
5962R9571401QXC	-55°C to +125°C	MIL-PRF-38535 Level Q	20 Lead Ceramic Flatpack
5962R9571401VRC	-55°C to +125°C	MIL-PRF-38535 Level V	20 Lead SBDIP
5962R9571401VXC	-55°C to +125°C	MIL-PRF-38535 Level V	20 Lead Ceramic Flatpack
HS1-82C08RH/SAMPLE	+25°C	SAMPLE	20 Lead SBDIP
HS9-82C08RH/SAMPLE	+25°C	SAMPLE	20 Lead Ceramic Flatpack

Pinouts

20 LEAD CERAMIC DUAL-IN-LINE
METAL-SEAL PACKAGE (SBDIP) MIL-STD-1835, CDIP2-T20
TOP VIEW

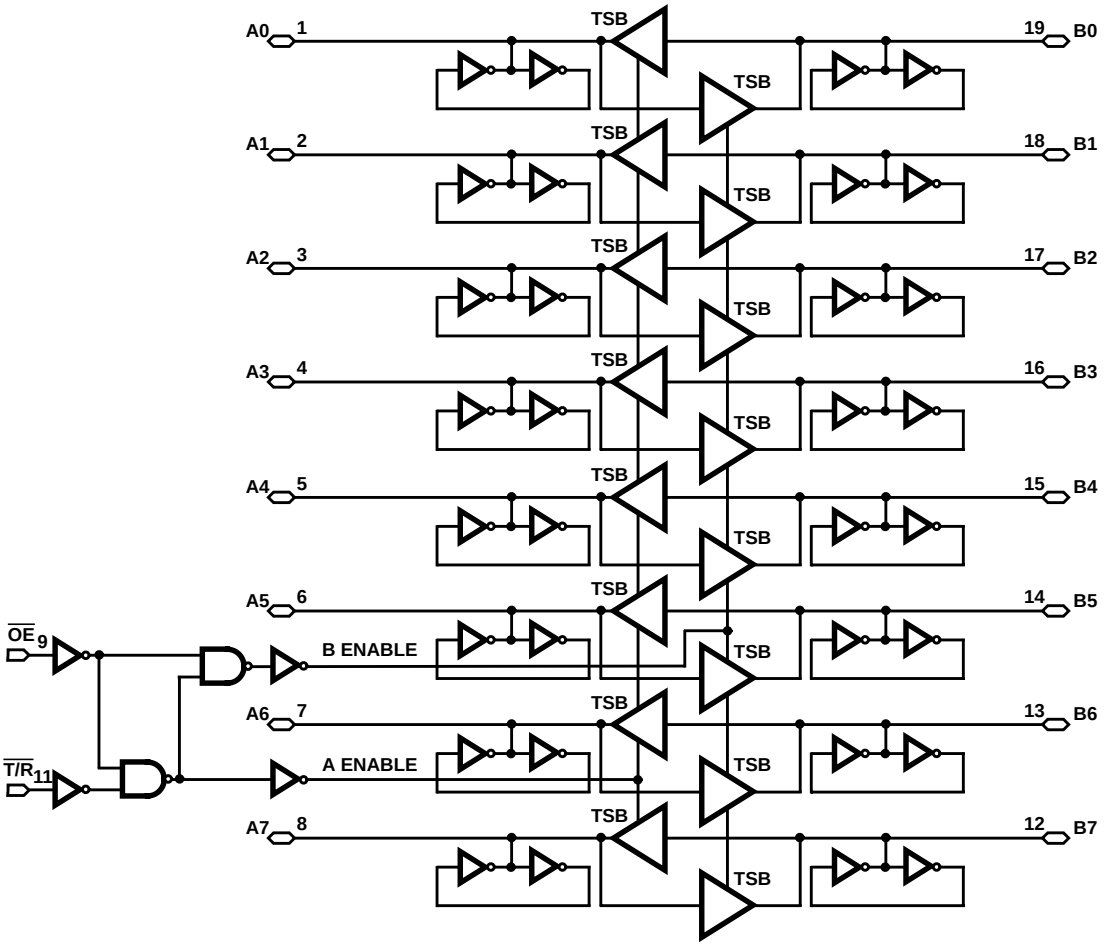


20 LEAD CERAMIC METAL SEAL
FLATPACK PACKAGE (FLATPACK) MIL-STD-1835, CDFP4-F20
TOP VIEW



PIN	DESCRIPTION	PIN	DESCRIPTION
A0-A7	Local Bus Data I/O Pins	T/$\overline{R}$	Transmit/Receive Input
B0-B7	System Bus Data I/O Pins	$\overline{OE}$	Active Low Output Enable

Logic Diagram



NOTE: An Important caveat that is applicable to CMOS devices in general is that unused inputs should never be left floating. This rule applies to inputs connected to a three-state bus. The need for external pull-up resistors during three-state bus conditions is eliminated by the presence of regenerative latches on the following HS-82C08RH pins. A0-7 and B0-7 The functional block diagram depicts one of these pins with the regenerative latch. When the CMOS driver assumes the high impedance state, the latch holds the bus in whatever logic state (high or low) it was before the three-state condition. A transient drive current of ±1.5mA at VDD/2 ±0.5V for 10ns is required to switch the latch. Thus, CMOS device inputs connected to the bus are not allowed to float during three-state conditions.

Absolute Maximum Ratings

Supply Voltage . . . . . +7.0V
Input, Output or I/O Voltage . . . . . GND-0.3V to VDD+0.3V
Storage Temperature Range . . . . . -65^oC to $+150^oC$
Junction Temperature . . . . . $+175^oC$
Lead Temperature (Soldering 10s) . . . . . $+300^oC$
ESD Classification . . . . . Class 1

Reliability Information

Thermal Resistance	θ_{JA}	θ_{JC}
20 Lead SBDIP Package	$71^oC/W$	$17^oC/W$
20 Lead Ceramic Flatpack Package	$85^oC/W$	$25^oC/W$

Maximum Package Power Dissipation at $+125^oC$ Ambient
20 Lead SBDIP Package 0.70W
20 Lead Ceramic Flatpack Package 0.59W
If device power exceeds package dissipation capability, provide heat sinking or derate linearly at the following rate:
20 Lead SBDIP Package 14.1mW/C
20 Lead Ceramic Flatpack Package 11.8mW/C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Operating Conditions

Operating Voltage Range . . . . . +4.75V to +5.25V
Operating Temperature Range . . . . . -55^oC to $+125^oC$
Input Low Voltage . . . . . 0V to +1V
Input High Voltage . . . . . VDD -1V to VDD

TABLE 1. DC ELECTRICAL PERFORMANCE CHARACTERISTICS

All Devices Guaranteed at Worst Case Limits and Conditions.

PARAMETER	SYMBOL	CONDITIONS	GROUP A SUBGROUPS	TEMPERATURE	LIMITS		UNITS
					MIN	MAX	
Input Leakage Current	IIL	VDD = 5.25V, VIN = VDD Pin Under Test = 0V	1, 2, 3	-55^oC, $+25^oC$, $+125^oC$	-1.0	-	µA
	IIH	VDD = 5.25V, VIN = 0V Pin Under Test = 5.25V	1, 2, 3	-55^oC, $+25^oC$, $+125^oC$	-	1.0	µA
High Level Output Voltage	VOH	VDD = 4.75V, IOH = -2.0mA	1, 2, 3	-55^oC, $+25^oC$, $+125^oC$	4.25	-	V
Low Level Output Voltage	VOL	VDD = 5.25V, IOL = 2.0mA	1, 2, 3	-55^oC, $+25^oC$, $+125^oC$	-	0.5	V
Static Current	SIDD	VDD = 5.25V, VIN = GND	1, 2, 3	-55^oC, $+25^oC$, $+125^oC$	-	100	µA
Functional Test	FT	VDD = 4.75V to 5.25V VIH = VDD -1.0V, VIL = 1.0V	7, 8A, 8B	-55^oC, $+25^oC$, $+125^oC$	-	-	-

TABLE 2. AC ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	GROUP A SUBGROUPS	TEMPERATURE	LIMITS		UNITS
				MIN	MAX	
PORT DATA/MODE SPECIFICATIONS						
Propagation Delay to Logical "1" from Port A, B to Port B, A	TPDLH	9, 10, 11	-55^oC, $+25^oC$, $+125^oC$	-	65	ns
Propagation Delay to Logical "0" from Port A, B to Port B, A	TPDHL	9, 10, 11	-55^oC, $+25^oC$, $+125^oC$	-	80	ns
Propagation Delay from High-Impedance to Logical "1" from T/$\overline{R}$ to Port	TPRTH	9, 10, 11	-55^oC, $+25^oC$, $+125^oC$	-	75	ns
Propagation Delay from High-Impedance to Logical "0" from T/$\overline{R}$ to Port	TPRTL	9, 10, 11	-55^oC, $+25^oC$, $+125^oC$	-	130	ns
Propagation Delay from High-Impedance to Logical "1" from $\overline{OE}$ to Port	TPZH	9, 10, 11	-55^oC, $+25^oC$, $+125^oC$	-	70	ns
Propagation Delay from High-Impedance to Logical "0" from $\overline{OE}$ to Port	TPZL	9, 10, 11	-55^oC, $+25^oC$, $+125^oC$	-	130	ns

TABLE 3. ELECTRICAL PERFORMANCE CHARACTERISTICS

PARAMETER	SYMBOL	(NOTE) CONDITIONS	TEMPERATURE	LIMITS MIN	LIMITS MAX	UNITS
In/Out Capacitance	CI/O	VDD = Open, f = 1MHz All Measurements Referenced to GND.	+25°C	-	10	pF
TRANSMIT/RECEIVE MODE SPECIFICATIONS (AC Parameters)						
Propagation Delay from Logical “1” to High-Impedance from T/$\overline{R}$ to Port	TPHZTR		+25°C	-	35	ns
Propagation Delay from Logical “0” to High-Impedance from T/$\overline{R}$ to Port	TPLZTR		+25°C	-	35	ns
Propagation Delay from Logical “1” to High-Impedance from $\overline{OE}$ to Port	TPHZ		+25°C	-	35	ns
Propagation Delay from Logical “0” to High-Impedance from $\overline{OE}$ to Port	TPLZ		+25°C	-	35	ns

NOTE:

1. The parameters listed are controlled via design or process parameters and are not directly tested. These parameters are characterized upon initial design release and upon design changes which could affect these characteristics.

TABLE 4. POST 100K RAD ELECTRICAL PERFORMANCE CHARACTERISTICS

NOTE: The Post Irradiation test conditions and limits are the same as those listed in Table 1 and Table 2.

TABLE 5. BURN-IN DELTA PARAMETERS (+25°C; In Accordance With SMD)

Switching Time Waveforms

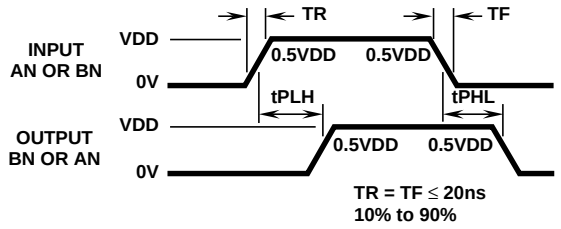
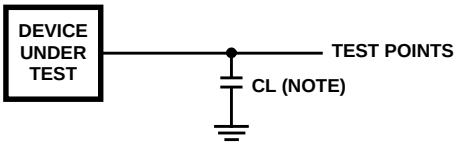


FIGURE 1. PORT TO PORT



NOTE: CL includes stray and jig capacitance.

FIGURE 2. AC TESTING LOAD CIRCUIT

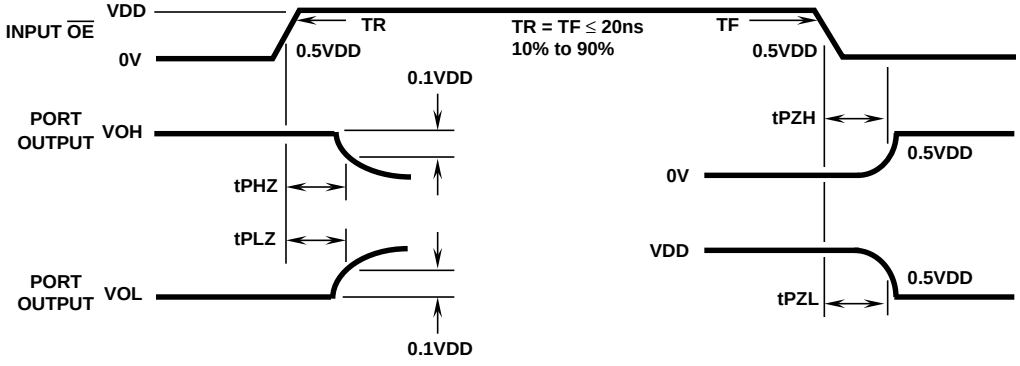


FIGURE 3. $\overline{OE}$ TO HIGH-IMPEDANCE, $\overline{OE}$ TO PORT OUTPUT

Metallization Topology

DIE DIMENSIONS:

76.0 mils x 89.4 mils x 14 mils ±1 mil

METALLIZATION:

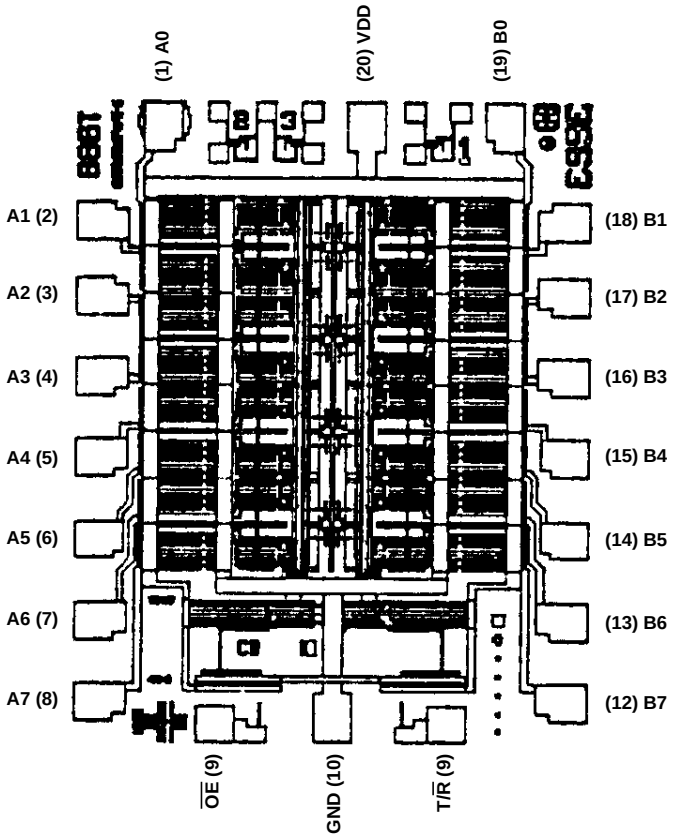
Type: Si - Al
Thickness: 11kÅ ±2kÅ

GLASSIVATION:

Type: SiO_2
Thickness: 8kÅ ±1kÅ

Metallization Mask Layout

HS-82C08RH



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Sales Office Headquarters

NORTH AMERICA
Intersil Corporation
P. O. Box 883, Mail Stop 53-204
Melbourne, FL 32902
TEL: (407) 724-7000
FAX: (407) 724-7240

EUROPE
Intersil SA
Mercure Center
100, Rue de la Fusee
1130 Brussels, Belgium
TEL: (32) 2.724.2111
FAX: (32) 2.724.22.05

ASIA
Intersil (Taiwan) Ltd.
Taiwan Limited
7F-6, No. 101 Fu Hsing North Road
Taipei, Taiwan
Republic of China
TEL: (886) 2 2716 9310
FAX: (886) 2 2715 3029